


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

| | | |
|----------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | POWER AND DISCRETE PRODUCTS/25/15161 | |
| 1.3 Title of PCN | Qualification of the new Lead Frame and soft solder dispenser tool for selected MOSFET LV products in TO252 (DPAK) in TFME plant. | |
| 1.4 Product Category | Pls Refer to the Products List (MOSFET LV) | |
| 1.5 Issue date | 2025-02-04 | |

2. PCN Team

| | |
|----------------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Rosario RUGGERI |
| 2.1.2 Marketing Manager | Anna RANIOLO |
| 2.1.3 Quality Manager | Daniela FAZIO |

3. Change

| | | |
|---------------------|---|-----------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Materials | New direct material part number r (same supplier, different supplier or new supplier),(Lead frame dimensions) | 998G (TFME) |

4. Description of change

| | | |
|---|---|--|
| | Old | New |
| 4.1 Description | Standard DPAK Leadframe TO252-3H + Soft Solder dispenser PUM. | New DPAK Leadframe TO252-3U + Soft Solder dispenser SPANKER. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No Impact | |

5. Reason / motivation for change

| | |
|----------------------|--|
| 5.1 Motivation | To continuously improve our service and to rationalize and optimize Power MOSFET Transistors productivity. |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT |

6. Marking of parts / traceability of change

| | |
|-----------------|---------------|
| 6.1 Description | Dedicated FGs |
|-----------------|---------------|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2024-12-20 |
| 7.2 Intended start of delivery | 2025-04-01 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | | | |
|--|---|------------|------------|
| 8.1 Description | 15161 RERLVIP24034_1.0_New_LF_TO252-3U_Die_attached_Spanker_DPAK_TFME.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2025-02-04 |

9. Attachments (additional documentations)

15161 Public product.pdf
15161 New Lead Frame and soft solder tool for LV in TO252 (DPAK) in TFME plant .pdf
15161 RERLVIP24034_1.0_New_LF_TO252-3U_Die_attached_Spanker_DPAK_TFME.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STD20NF20 | |
| | STD40NF10 | |
| | STD60NF06T4 | |

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